



PRESS RELEASE

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IMAPS Device Packaging Conference Returns to Arizona in March 2023

The Most Comprehensive Program for Microelectronics and Advanced Packaging This Spring

The 19th Annual Device Packaging Conference (DPC 2023) will be held March 13-16, 2023, at the WeKoPa Resort and Conference Center in Fountain Hills, Arizona. This esteemed event brings together industry engineers, researchers and top experts involved in advanced packaging and microelectronics assembly with a multi-faceted technical program and unique networking events.

The technical content includes an unrivaled, concurrent 3-track program with over 80 speakers and poster presentations covering topics related to Heterogeneous Integration, Fan-Out, Wafer Level Packaging & Flip Chip, and Next Gen Application (Automotive, 5G/6G, Photonics, HiSpeed RF). Attendees will enjoy four keynote speakers from Qualcomm, Samsung, General Motors, and Lightmatter, a panel on *Packaging Solutions to Address High Performance Computing Challenges* and a business plenary session on *Building the Ecosystem: Transitioning from Research to Manufacturing*.

Attendees can also register for 12 Professional Development Courses. These focused courses provide a learning opportunity for those new to the industry or looking to enhance their skills and knowledge.

A sold-out exhibit hall will feature 66 booths showcasing the latest product and service applications of the current technologies. Registration includes many networking opportunities that promote attendee interaction: a welcome reception, exhibit hall reception, group lunches, and a DEI Roundtable session. A post-conference golf scramble and guided hike will be offered to raise funds for the IMAPS Microelectronics Foundation and the 3D InCites DEI Fund, respectively.

In 2022, DPC was held in person with more than 500 participants, despite continued pandemic restrictions at that time. Given the strength of the technical program and exhibition this year, it is anticipated that the 2023 DPC will welcome a record number of participants.

Early registration pricing ends February 1 and hotel rooms will book quickly. Conference details and registration are available at <http://www.devicepackaging.org>

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